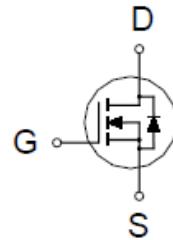
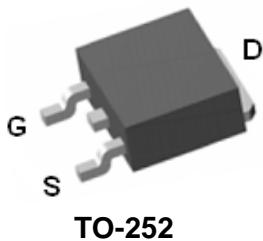


# P1820HDB

## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
200V	157mΩ @ $V_{GS} = 10V$	18A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	200	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	18	A
	$T_C = 100^\circ C$		9	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	30	A
Avalanche Current		$I_{AS}$	12	
Avalanche Energy	$L = 1mH$	$E_{AS}$	72	mJ
Power Dissipation	$T_C = 25^\circ C$	$P_D$	83	W
	$T_C = 100^\circ C$		33	
Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	1.5	1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

# P1820HDB

## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

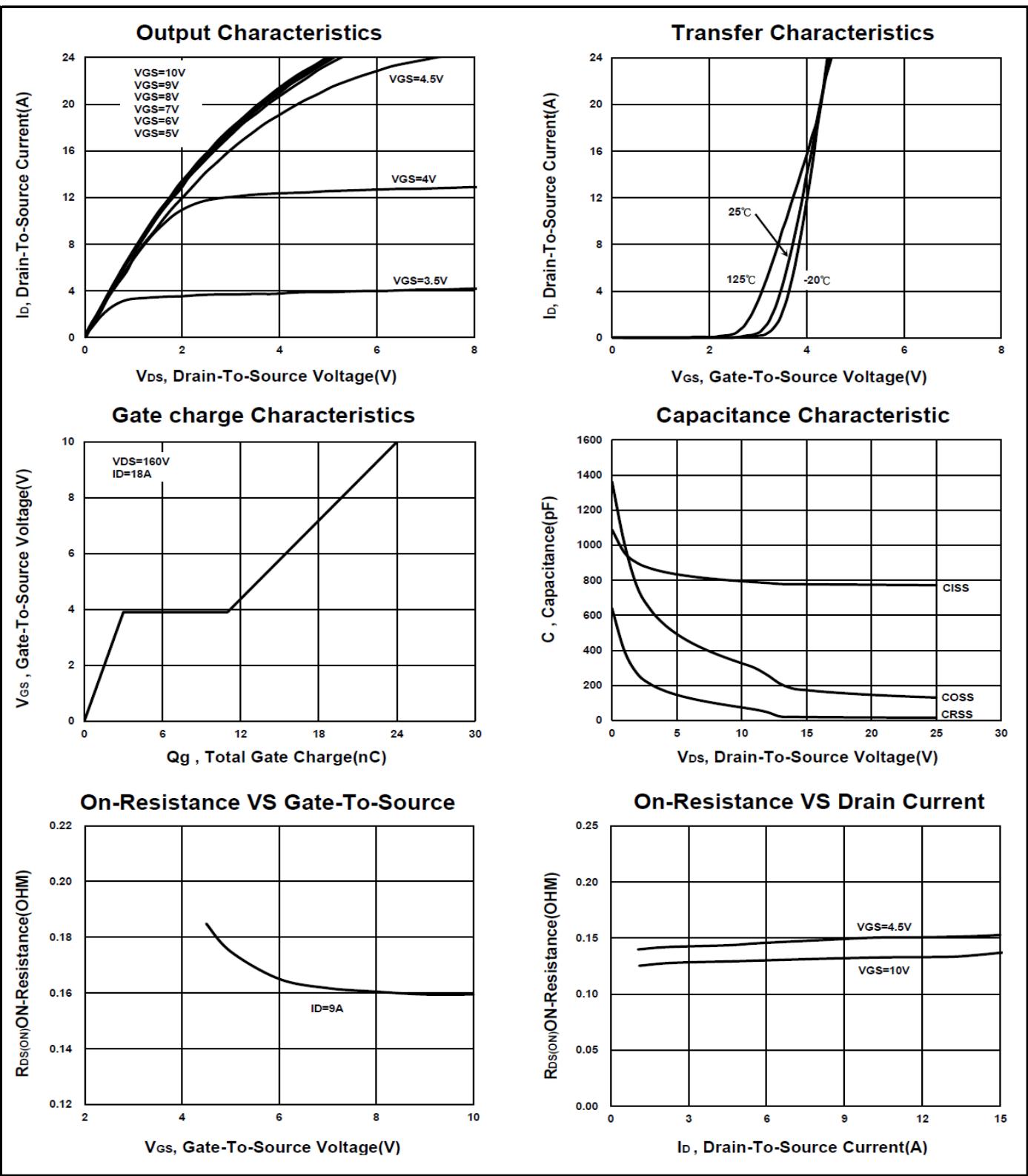
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	2	3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 9\text{A}$		148	188	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$		131	157	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 10\text{V}, I_D = 9\text{A}$		21		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		780		pF
Output Capacitance	$C_{\text{oss}}$			132		
Reverse Transfer Capacitance	$C_{\text{rss}}$			16		
Total Gate Charge <sup>2</sup>	$Q_g(V_{\text{GS}} = 10\text{V})$	$V_{\text{DS}} = 160\text{V}, I_D = 18\text{A}$		24		nC
	$Q_g(V_{\text{GS}} = 4.5\text{V})$			12		
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			3		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			8		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d(on)}}$	$V_{\text{DS}} = 100\text{V}, I_D \geq 18\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		20		nS
Rise Time <sup>2</sup>	$t_r$			135		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d(off)}}$			176		
Fall Time <sup>2</sup>	$t_f$			128		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				18	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = 18\text{A}, V_{\text{GS}} = 0\text{V}$			1	V
Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 18\text{A}, dI/dt = 100\text{A} / \mu\text{s}$		122		nS
Diode Reverse Recovery Charge	$Q_{\text{rr}}$			0.67		uC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

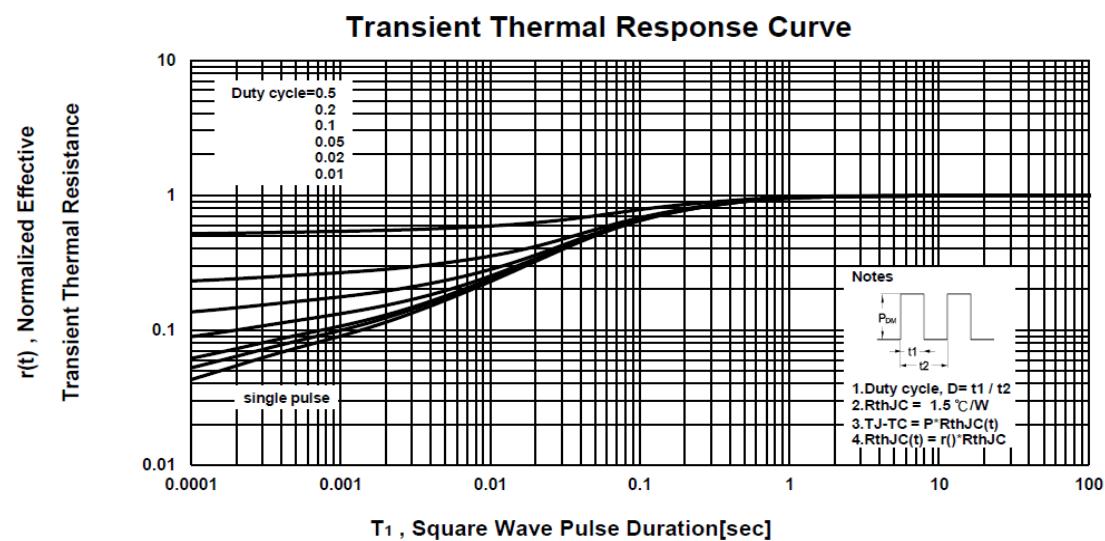
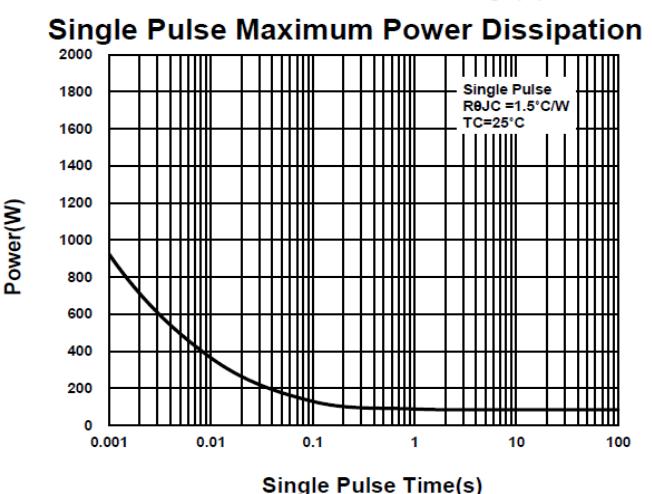
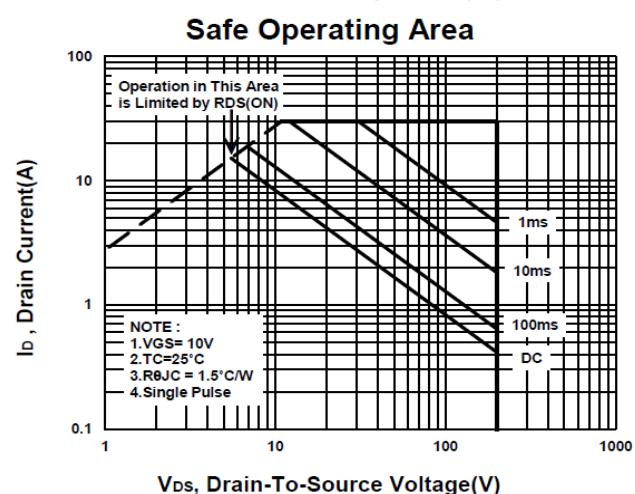
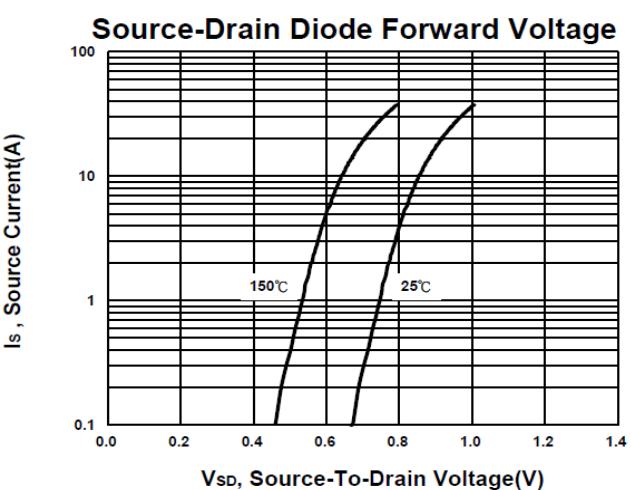
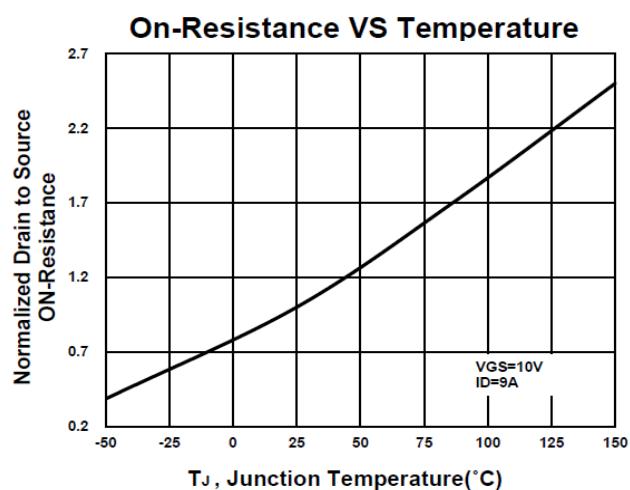
## P1820HDB

### N-Channel Enhancement Mode MOSFET



## P1820HDB

### N-Channel Enhancement Mode MOSFET



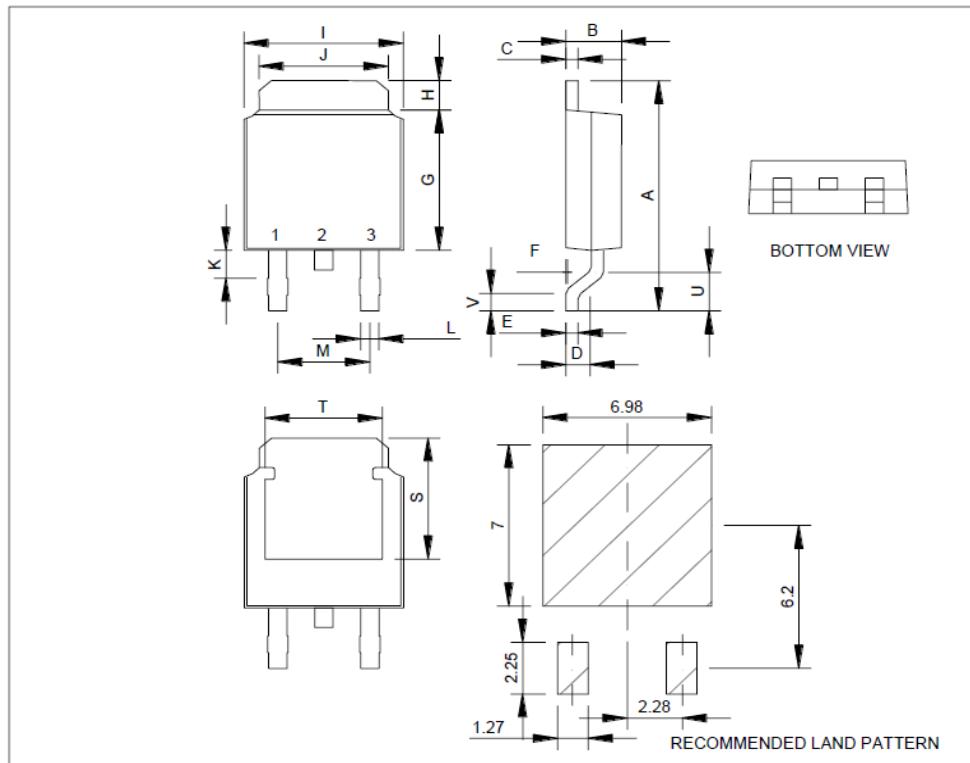
## P1820HDB

### N-Channel Enhancement Mode MOSFET

#### Package Dimension

#### TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.4	K	0.15		1.1
C	0.4	0.5	0.61	L	0.4	0.76	0.89
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.4	0.5	0.61	S	4.9	5.1	5.3
F	0		0.2	T	4.6	4.75	5.44
G	5.3	6.1	6.3	U	1.4		1.78
H	0.9		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				

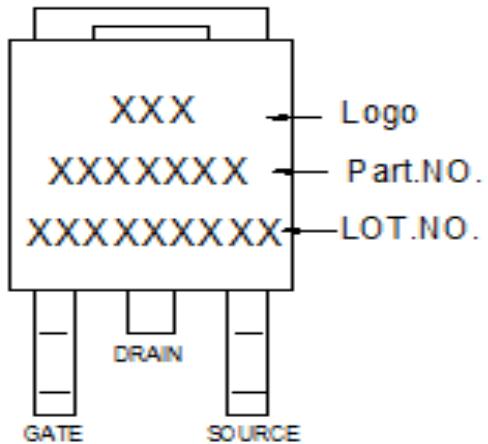


\*因为各家封装模具不同而外观略有差异，不影响电性及Layout。

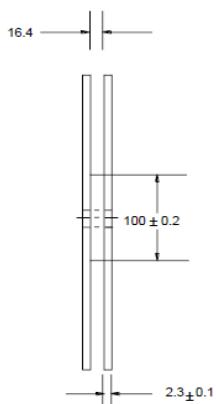
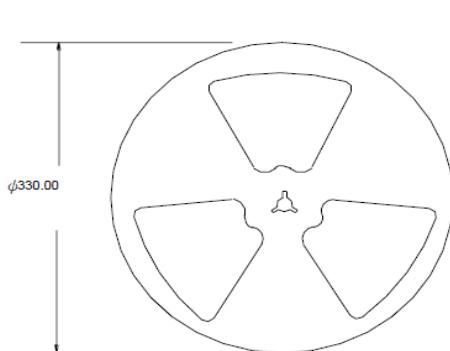
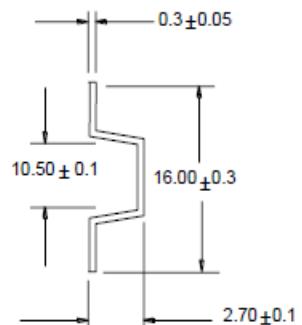
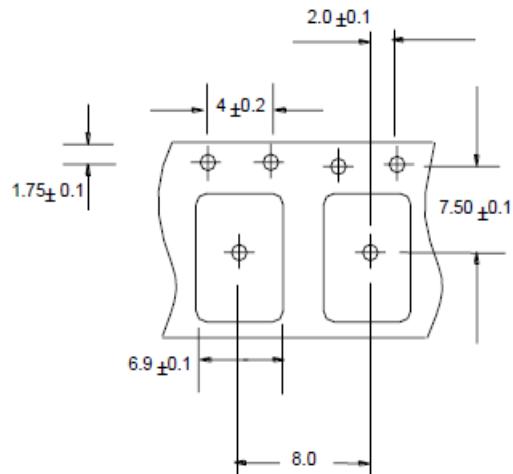
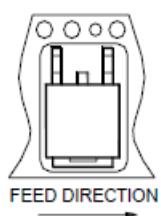
## P1820HDB

### N-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 2500pcs/Reel

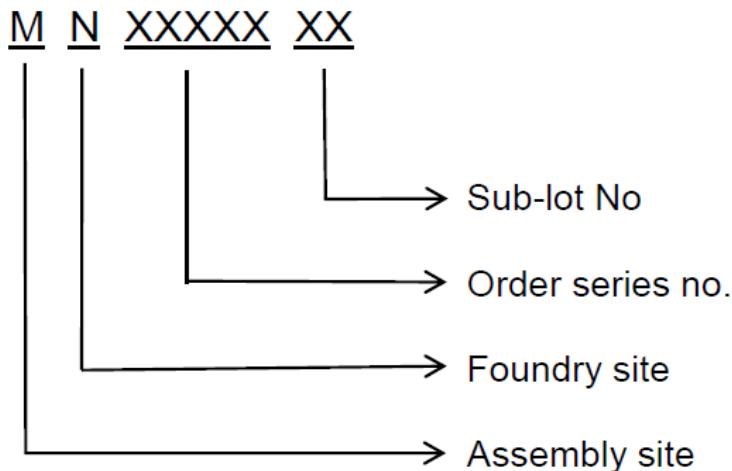


## P1820HDB

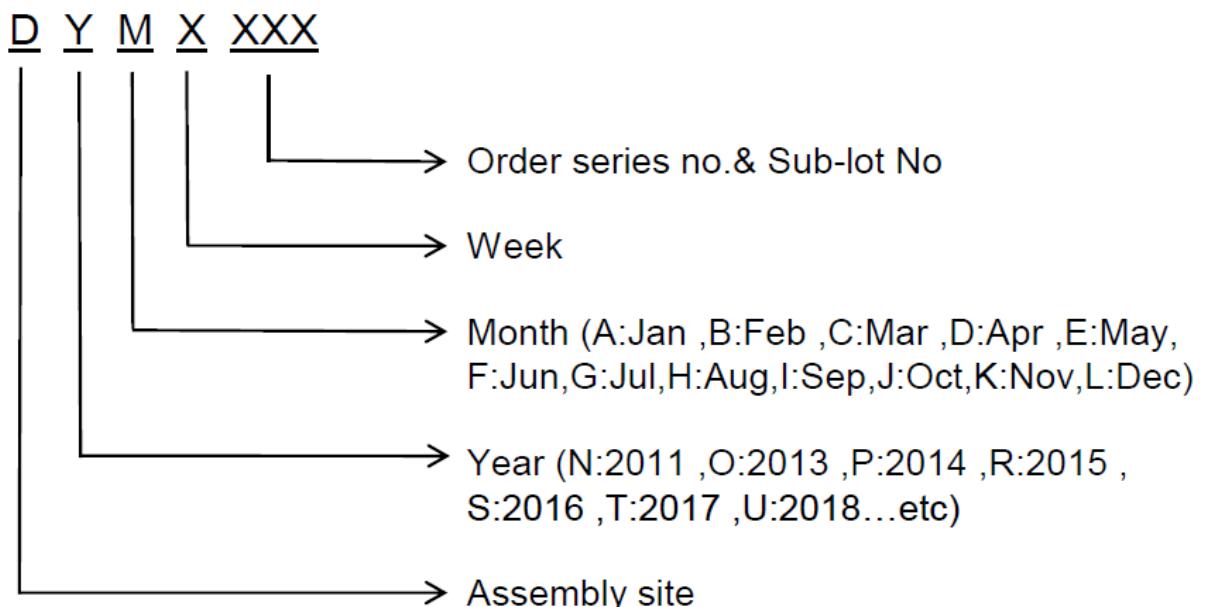
### N-Channel Enhancement Mode MOSFET

#### C. Lot No.&Date Code rule

##### 1. Lot No.



##### 2. Date Code



## P1820HDB

### N-Channel Enhancement Mode MOSFET

#### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least